

## **Features**

- Low R<sub>DS(on)</sub> and FOM
- · Extremely Low Switching Loss
- · Excellent Stability and Uniformity
- · Fast Switching and Soft Recovery
- · Epoxy Meets UL 94 V-0 Flammability Rating
- · Moisture Sensitivity Level 1
- Halogen Free Available Upon Request By Adding Suffix "-HF"
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

# **Maximum Ratings**

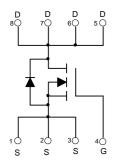
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 31°C/W Junction to Ambient<sup>(Note1)</sup>

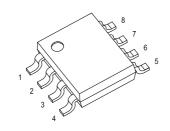
Parameter	Symbol	Rating	Unit	
Drain-Source Voltage	V <sub>DS</sub>	100	V	
Gate-Source Volltage	$V_{GS}$	±20	V	
Continuous Drain Current <sup>(Note2)</sup>	I <sub>D</sub>	15	Α	
Pulsed Drain Current <sup>(Note3)</sup>	I <sub>DM</sub>	64	Α	
Total Power Dissipation <sup>(Note4)</sup> T <sub>C</sub> =25°C	В	4	10/	
T <sub>C</sub> =100°C	P <sub>D</sub> 1.6		W	
Single Pulsed Avalanche Energy <sup>(Note5)</sup>	E <sub>AS</sub>	130	mJ	

## Note:

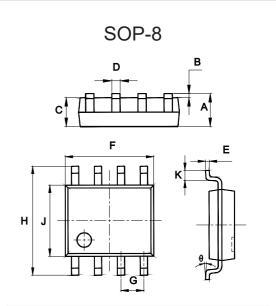
- 1. The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A$ =25 °C.
- 2. Calculated continuous current based on maximum allowable junction temperature.
- 3. Repetitive rating; pulse width limited by max. junction temperature.
- 4. PD is based on max. junction temperature, using junction-case thermal resistance.
- 5.  $V_{DD}$ =50V,  $R_G$ =50 $\Omega$ , L=0.3mH, starting  $T_J$ =25°C.

## **Internal Structure:**



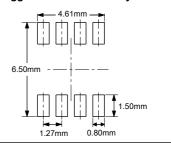


# N-Channel Enhancement Mode Field Effect Transistor



DIMENSIONS					
DIM	INCHES		MM		NOTE
DIIVI	MIN	MAX	MIN	MAX	INOTE
Α	0.053	0.069	1.35	1.75	
В	0.004	0.010	0.10	0.25	
С	0.053	0.061	1.35	1.55	
D	0.013	0.020	0.33	0.51	
E	0.007	0.010	0.17	0.25	
F	0.185	0.200	4.70	5.10	
G	0.050	0.050 BSC		BSC	
Н	0.228	0.244	5.80	6.20	
J	0.150	0.157	3.80	4.00	
K	0.016	0.050	0.40	1.27	
θ	0°	8°	0°	8°	

### Suggested Solder Pad Layout



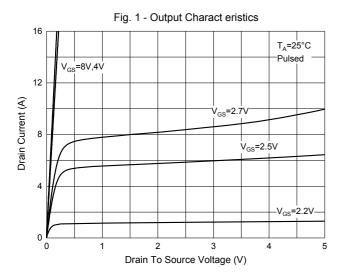


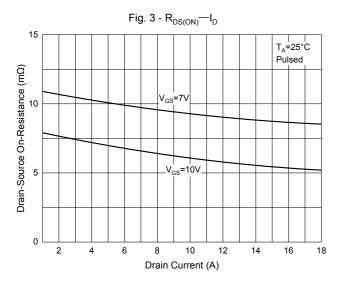
# Electrical Characteristics @ 25°C (Unless Otherwise Specified)

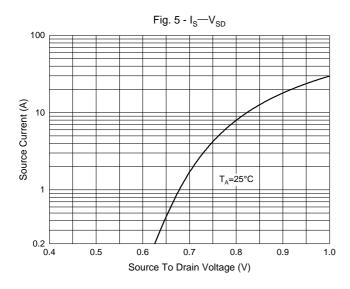
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static Characteristics				1			
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100			V	
Gate-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0V, V_{GS} = \pm 20V$			±100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V			1	μΑ	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_D=250\mu A$	1	1.8	2.5	V	
	Б	V <sub>GS</sub> =10V, I <sub>D</sub> =12A		7.7	9.5	mΩ	
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =9A		9.2 12.5		11122	
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =15A			1.3	V	
Maximum Body-Diode Continuous Current	I <sub>S</sub>				15	А	
Dynamic Characteristics							
Input Capacitance	C <sub>iss</sub>			3530		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ =50V, $V_{GS}$ =0V,f=1MHz		560			
Reverse Transfer Capacitance	C <sub>rss</sub>			9			
Switching Characteristics				1			
Total Gate Charge	$Q_g$			60.7			
Gate-Source Charge	$Q_{gs}$	V <sub>DS</sub> =50V,V <sub>GS</sub> =10V,I <sub>D</sub> =10A		7.2		nC	
Gate-Drain Charge	$Q_{gd}$			14.6			
Reverse Recovery Chrage	Q <sub>rr</sub>	L =10.4 di/dt=100.4/up		160			
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> =10A, di/dt=100A/μs		67			
Turn-On Delay Time	t <sub>d(on)</sub>			22.5			
Turn-On Rise Time	t <sub>r</sub>	\/ -10\/\/ -50\/\ -10^		8.6		ns	
Turn-Off Delay Time	$t_{d(off)}$	V <sub>GS</sub> =10V,V <sub>DD</sub> =50V,I <sub>D</sub> =10A		66.6			
Turn-Off Fall Time	t <sub>f</sub>			42.1			

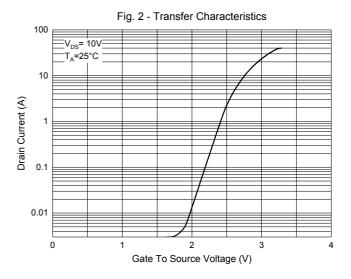


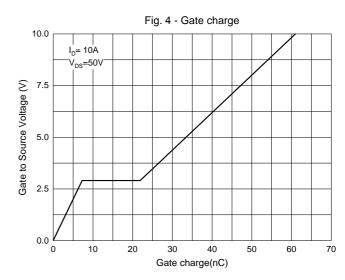
## **Curve Characteristics**

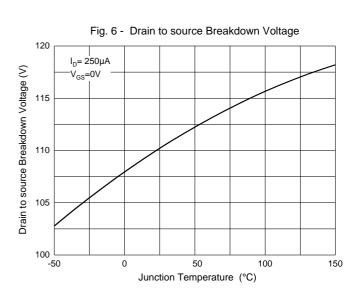














## **Ordering Information**

Device	Packing
Part Number-TP	Tape&Reel: 4Kpcs/Reel

Note: Adding "-HF" Suffix For Halogen Free, eg. Part Number-TP-HF

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